

Amendments to the Claims

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

LISTING OF CLAIMS:

1. (Currently Amended) A structure for providing resilient interconnections in a wafer level package, comprising a conductive pad that directly overlays an air space, wherein at least a portion of the air space extends laterally beyond the conductive pad.
2. (Original) The structure as claimed in claim 1, wherein the air space comprises a geometric structure having a plurality of perimeter interconnect support structures for the conductive pad.
3. (Original) The structure as claimed in claim 2, wherein at least one perimeter interconnect support structure also supports a conductive line electrically connected to the conductive pad.
4. (Original) The structure as claimed in claim 3, wherein the conductive line is a metal wire.
5. (Original) The structure as claimed in claim 1, wherein a major axis of the air space is radial to a center of the wafer level package.
6. (Original) The structure as claimed in claim 1, wherein a major axis of the air space is not radial to a center of the wafer level package.
- 7-20. (Cancelled).